

#### **Dual 1-of-4 Decoder / Demultiplexer in bare die form**

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### Description

The 74HC139 is fabricated using a 2.5µm 5V CMOS process and has the same high speed performance of LSTTL combined with CMOS low power consumption. This device consists of x2 independent 1–of–4 decoders, each decoding a 2 bit address to 1–of–4 active–low outputs. Active–low Selects facilitate the demultiplexing and cascading functions. The demultiplexing function is executed by using the Address inputs to select the desired device output and utilizing the Select as a data input.

#### Features:

Output Drive Capability: 10 LSTTL Loads

■ Low Input Current: 1µA

Outputs directly interface CMOS, NMOS and TTL

Operating Voltage Range: 2V to 6V

CMOS High Noise Immunity

Function compatible with 74LS139.

### **Ordering Information**

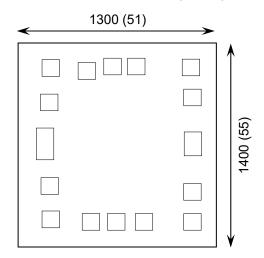
The following part suffixes apply:

No suffix - MIL-STD-883 /2010B Visual Inspection

For High Reliability versions of this product please see

54HC139

### Die Dimensions in µm (mils)



### **Supply Formats:**

- Default Die in Waffle Pack (400 per tray capacity)
- Sawn Wafer on Tape On request
- Unsawn Wafer On request
- Die Thickness <> 350µm(14 Mils) On request
- Assembled into Ceramic Package On request

### **Mechanical Specification**

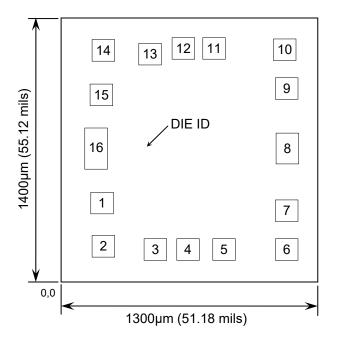
Die Size (Unsawn)	1300 x 1400 51 x 55	µm mils	
Minimum Bond Pad Size	106 x 106 4.17 x 4.17	μm mils	
Die Thickness	350 (±20) 13.78 (±0.79)	μm mils	
Top Metal Composition	Al 1%Si 1.1μ	m	
Back Metal Composition	N/A – Bare Si		



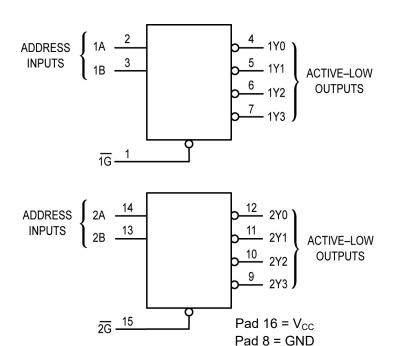


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### Pad Layout and Functions



### Logic Diagram



PAD	FUNCTION	COORDIN	ATES (mm)
FAD	FUNCTION	X	Y
1	1G	0.152	0.366
2	1A	0.162	0.132
3	1B	0.422	0.122
4	1Y0	0.59	0.122
5	1Y1	0.772	0.122
6	1Y2	1.088	0.122
7	1Y3	1.088	0.333
8	GND	1.088	0.619
9	2Y3	1.088	0.972
10	2Y2	1.078	1.173
11	2Y1	0.722	1.183
12	2Y0	0.566	1.183
13	2B	0.396	1.153
14	2A	0.162	1.173
15	2G	0.152	0.938
16	V <sub>CC</sub>	0.122	0.591
CON	NECT CHIP BA	CK TO V <sub>CC</sub> C	OR FLOAT

### **Truth Table**

IN	PUTS			OU	TPUTS	3
G	В	Α	Y0	Y1	Y2	Y3
Н	Х	Χ	Н	Н	Н	Н
L	L	L	L	Н	Н	Н
L	L	Н	H	L	Н	Н
L	Н	L	H	Н	L	Н
L	Н	Н	Н	Н	Н	L

X = don't care





## Absolute Maximum Ratings<sup>1</sup>

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PARAMETER	SYMBOL	VALUE	UNIT
DC Supply Voltage (Referenced to GND)	V <sub>CC</sub>	-0.5 to +7.0	V
DC Input Voltage (Referenced to GND)	V <sub>IN</sub>	-1.5 to V <sub>CC</sub> +1.5	V
DC Output Voltage (Referenced to GND)	V <sub>OUT</sub>	-0.5 to V <sub>CC</sub> +0.5	V
DC Input Current, per pin	I <sub>IN</sub>	±20	mA
DC Output Current, per pin	I <sub>OUT</sub>	±25	mA
DC V <sub>CC</sub> or GND Current, per pin	I <sub>CC</sub>	±50	mA
Power Dissipation in Still Air <sup>2</sup>	P <sub>D</sub>	750	mW
Storage Temperature Range	T <sub>STG</sub>	-65 to 150	°C

<sup>1.</sup> Operation above the absolute maximum rating may cause device failure. Operation at the absolute maximum ratings, for extended periods, may reduce device reliability. 2. Measured in plastic DIP package, results in die form are dependent on die attach and assembly method.

## Recommended Operating Conditions<sup>3</sup> (Voltages referenced to GND)

PARAMETER	SYMBOL	MIN	MAX	UNITS	
DC Supply Voltage		V <sub>CC</sub>	2	6	V
DC Input or Output Voltage		$V_{\text{IN}}$ , $V_{\text{OUT}}$	0	V <sub>CC</sub>	V
Operating Temperature Range		T <sub>J</sub>	0	+85	°C
	V <sub>CC</sub> = 2.0V		0	1000	
Input Rise and Fall Time	V <sub>CC</sub> = 4.5V	t <sub>r</sub> , t <sub>f</sub>	0	500	ns
	$V_{CC} = 6.0V$		0	400	

<sup>3.</sup> This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation,  $V_{IN}$  and  $V_{OUT}$  should be constrained to the range GND  $\leq$  ( $V_{IN}$  or  $V_{OUT}$ )  $\leq$   $V_{CC}$ . Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or  $V_{CC}$ ). Unused outputs must be left open.

### DC Electrical Characteristics (Voltages Referenced to GND)

PARAMETER	SYMBOL	SYMBOL V <sub>CC</sub> CONDITIONS	CONDITIONS		LIMITS		
			CONDITIONS	25°C	85°C	FULL RANGE⁴	UNITS
Minimum High-Level Input Voltage		2.0V V <sub>OUT</sub> = 0.1V or	1.5	1.5	1.5		
	V <sub>IH</sub>	4.5V	$V_{CC}$ -0.1V $ I_{OUT}  \le 20\mu A$	3.15	3.15	3.15	V
		6.0V		4.2	4.2	4.2	
Maximum Low-Level Input Voltage	v-Level	2.0V	V <sub>OUT</sub> = 0.1V or	0.5	0.5	0.5	
		4.5V	V <sub>CC</sub> -0.1V	1.35	1.35	1.35	V
		6.0V   I <sub>OUT</sub>   ≤ 20µA	I <sub>OUT</sub>   ≤ 20µA	1.8	1.8	1.8	

**<sup>4.</sup>**  $0^{\circ}C \le T_{J} \le +85^{\circ}C$ 





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### DC Electrical Characteristics (Voltages Referenced to GND)

PARAMETER	SYMBOL	V <sub>cc</sub> CONDITIONS		LIMITS			UNITS
		₩00	CONDITIONS	25°C	85°C	FULL RANGE⁴	Oiliio
		2.0V	1.9	1.9	1.9		
		4.5V	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $ I_{OUT}  \le 20 \mu A$	4.4	4.4	4.4	
Minimum High-Level		6.0V	1.0011 = = 4 km	5.9	5.9	5.9	
Output Voltage	V <sub>OH</sub>	4.5V	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $\left  I_{OUT} \right  \le 4.0 \text{mA}$	3.98	3.84	3.84	V
		6.0V	$\begin{array}{c c} V_{IN} = V_{IH} \text{ or } V_{IL} \\  I_{OUT}  \le 5.2 \text{mA} \end{array}$	5.48	5.34	5.34	
	V <sub>OL</sub> 2.0V 4.5V 6.0V 4.5V 6.0V	2.0V	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $\left  I_{OUT} \right  \le 20 \mu A$	0.1	0.1	0.1	
		4.5V		0.1	0.1	0.1	
Maximum Low-Level		6.0V		0.1	0.1	0.1	
Output Voltage		4.5V	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $\left  I_{OUT} \right  \le 4.0 \text{mA}$	0.26	0.33	0.33	V
		$V_{IN} = V_{IH} \text{ or } V_{IL}$ $\left  I_{OUT} \right  \le 5.2 \text{mA}$	0.26	0.33	0.33		
Maximum Input Leakage Current	I <sub>IN</sub>	6.0V	V <sub>IN</sub> = V <sub>CC</sub> or GND	±0.1	±1.0	±1.0	μA
Maximum Quiescent Supply Current	I <sub>CC</sub>	6.0V	$V_{IN} = V_{CC}$ or GND $I_{OUT} = 0\mu A$	4	40	40	μA

### AC Electrical Characteristics<sup>5</sup>

PARAMETER	SYMBOL	V <sub>cc</sub> CONDITIONS	LIMITS			UNITS	
17ttottile 12tt	01D02	• 66	CONDITIONS	25°C	85°C	FULL RANGE <sup>4</sup>	Citiro
Maximum		2.0V		115	145	145	
Propagation Delay, Select to Output Y	t <sub>PLH,</sub> t <sub>PHL</sub>	4.5V	$C_L = 50 pF,$ $t_r = t_f = 6 ns$	23	29	29	ns
(Figure 1, 3)		6.0V		20	25	25	
Maximum	t <sub>PLH</sub> , t <sub>PHL</sub>	2.0V	$C_L = 50pF,$ $t_r = t_f = 6ns$	115	145	145	
Propagation Delay, Input A to Output Y		4.5V		23	29	29	ns
(Figure 2,3)		6.0V		20	25	25	
Maximum Output		2.0V	0 50 5	75	95	95	
Transition Time, Any Output	t <sub>TLH</sub> , t <sub>THL</sub>	4.5V	$C_L = 50 pF,$ $t_r = t_f = 6 ns$	15	19	19	ns
(Figure 1,3)	6.0V		13	16	16		
Maximum Input Capacitance	C <sub>IN</sub>	-	-	10	10	10	pF
Power Dissipation			T <sub>J</sub> = 25°C,		TYPI	CAL	
Capacitance (Per Decoder) <sup>7</sup>	C <sub>PD</sub>	-	$V_{CC} = 5.0V$		5	5	pF

<sup>6.</sup> Not production tested in die form, characterized by chip design and tested in package.



<sup>7.</sup> Used to determine the no-load dynamic power consumption:  $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$ .



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### **Pad Description**

**ADDRESS INPUTS** 

1A, 1B, 2A, 2B

(Pads 2, 3, 14, 13)

When the respective 1-of-4 decoder is enabled these inputs determine which of its four active-low outputs is selected.

#### **CONTROL INPUTS**

1G, 2G

(Pads 1, 15)

Active—low select inputs. For a low level on this input, the outputs for that particular decoder follow the Address inputs. A high level on this input forces all outputs to a high level.

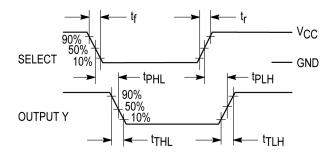
#### **OUTPUTS**

1Y0, 1Y1, 1Y2, 1Y3, 2Y0, 2Y1, 2Y2, 2Y3

(Pads 4-7, 12, 11, 10, 9)

Active—low outputs. These outputs assume a low level when addressed and the appropriate Select input is active. These outputs remain high when not addressed or the appropriate Select input is inactive.

### Switching Waveforms



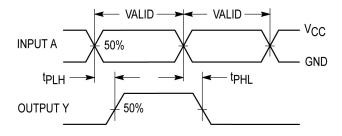
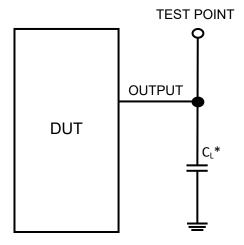


Figure 1

Figure 2

### **Test Circuit**



<sup>\*</sup> Includes all probe and jig capacitance





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